FSA0850 Series

High Current Molded Power Inductors



FEATURES

- Powder iron core material
- Magnetically shielded, low EMI
- High current carrying capacity, Low core losses
- Frequency range up to 3MHz
- Operate temperature range -40° C \sim +125 $^{\circ}$ C (Including self temp. rise)
- RoHS compliant





APPLICATIONS

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- Point-of-load modules
- Smart phone POL modules
- SSD modules
- Notebook regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems

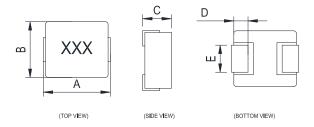
PRODUCT IDENTIFICATION

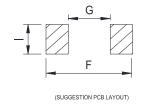
FSA 0850 - 2R2 M T

- 1 2
- 3 (4) (5)
- Series Name: Metal Alloy Molding Power Inductor Á
- ② Dimensions:
- ③ Initial inductance value: 2R2 = 2.2uH
- (4) Inductance Tolerance:M±20%
- ⑤ Packing: Tape & Reel



Dimensions: [mm]





Series	Α	В	С	D	Е	I Тур.	GTyp.	F Тур.
FSA0850	9.20Max	8.0±0.30	5.0Max	1.8±0.5	3.0±0.5	3.5	4.5	9.8

Electrical Properties:

Part Number	Inductance	DC Resistance	Saturation Current	Heat Rating Current	
	@1MHz,1V	Max.	Typ.	Тур.	
Units	μH	mΩ	A	Α	
Symbol	L	DCR	Isat	Irms	
FSA0850-R68MT	0.68±20%	4.5	26.0	20.0	
FSA0850-1R5MT	1.5±20%	7.0	17.0	16.0	
FSA0850-2R2MT	2.2±20%	9.0	15.0	14.0	
FSA0850-3R3MT	3.3±20%	12	13.0	8.8	
FSA0850-4R7MT	4.7±20%	19	11.0	10.0	
FSA0850-6R8MT	6.8±20%	22	10.0	9.0	
FSA0850-100MT	10.0±20%	30	8.0	7.0	
FSA0850-150MT	15±20%	65	6.0	5.0	
FSA0850-220MT	22±20%	80	5.0	4.0	
FSA0850-270MT	27±20%	182	4.5	3.0	
FSA0850-330MT	33±20%	130	4.0	2.0	
FSA0850-470MT	47±20%	247	3.3	2.0	
FSA0850-560MT	56±20%	250	3.0	1,8	
FSA0850-680MT	68±20%	270	2.8	<u>1.</u> 6	

Notes

- %1: All test data is referenced to 20°C ambient;
- %2: Irms:DC current (A)that will cause an approximate ΔT of 40 ℃ (Typical)
- *3:Isat:DC current (A) that will cause Lo to drop approximately 30%(Typical)
- %4: Inductance tolerance ±20%.1MHz and 1Vrms.
- %5: The rated current as listed is either the saturation current or the heating current depending on whith value is lower.
- %6: Absolute maximum voltage 30VDC

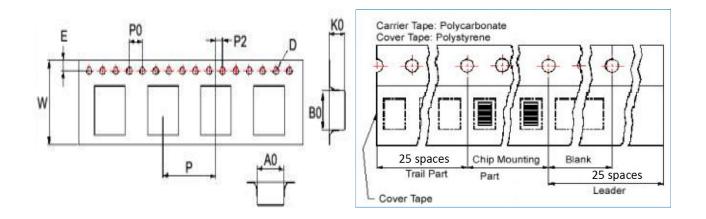


Reliability and Test Condition

Item	Specification and Requirement	Test Method				
	The surface of terminal immersed shall	Solder heat proof:				
Solderability	be minimum of 95% covered with a new	1. Preheating: 160 ± 10 $^{\circ}$ C				
	coating of solder	2. Retention time: 245 ± 5 °C for 2 ± 0.5 seconds				
Vibration		Vibration frequency:				
	Inductance change: Within ± 10%	(10 Hz to 55 Hz to 10Hz) in 60 seconds as a period				
	Without mechanical damage such as	2. Vibration time:				
Vibration	break	Period cycled for 2 hours in each of 3 mutual				
	break	perpendicular directions.				
		3. Amplitude: 1.5 mm max.				
		1. Peak value: 100 G				
Shock	Inductance change: Within ±10% Without	t 2. Duration of pulse: 11ms				
SHOOK	mechanical damage such as break	3. 3 times in each positive and negative direction of 3				
		mutual perpendicular directions				
ndurance Reli	ability					
Item	Specification and Requirement	Test Method				
		1. Repeat 100 cycles as follow:				
	Inductance change: Within ± 10% Without distinct damage in appearance	(-55 ± 2 °C; 30 ± 3 min)				
Thermal		→(Room temp., 5 min)				
Shock		\rightarrow (+125 ± 2 °C, 30 ± 3 min)				
Shock		→ (Room temp., 5 min)				
		2. Recovery: 48 + 4 / -0 hours of recovery under the				
		standard condition after the test.				
High	Inductance change: Within ± 10%	1. Environment condition: 85 ± 2 ℃				
Temperature	Without distinct damage in appearance	Applied Current: Rated current				
Resistance	Without distinct damage in appearance	2. Duration: 1000 + 4 / -0 hours				
		1. Environment condition: 60 ± 2 °C				
Humidity	Inductance change: Within ± 10%	Humidity: 90–95%				
Resistance	Without distinct damage in appearance	Applied Current: Rated current				
		2. Duration: 1000 + 4 / -0 hours				
Low	Inductance change: Within ± 10%	Store temperature:				
Temperature	Without distinct damage in appearance	-55 ± 2 °C,1000 + 4 / -0 hours				
Store	without distinct damage in appearance	-33 ± 2 €,1000 ± 4 / -0 Hours				
High	Inductance change: Within ± 10%	Store temperature:				
Temperature	Without distinct damage in appearance	Store temperature: +125 ± 2 ℃,1000 + 4 / -0 hours				
Store	vinious distinct damage in appearance	120 ± 2 0,1000 ± 47 =0 110u15				

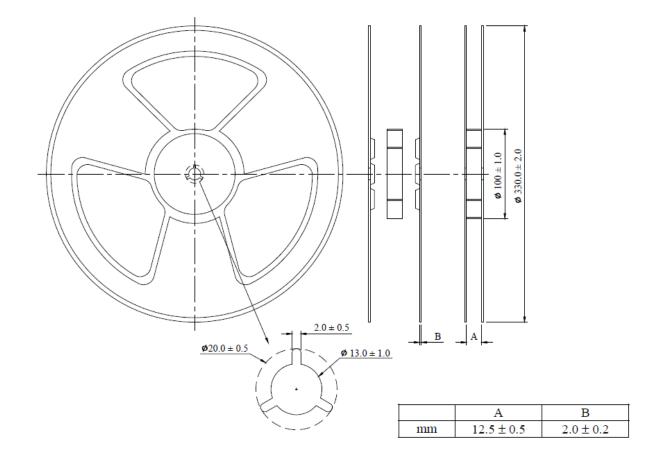


Tape Packaging Dimensions



Size	Ao(mm)	Bo(mm)	Ko(mm)	D(mm)	E(mm)	W(mm)	P(mm)	PO(mm)	P2(mm)
850	8.5	9.5	5.3	1.55	1.75	24	16	4	2

Reel Dimensions



Packing Quantity:1000pcs/Reel



Peak 260°C max

Recommended Soldering Technologies

(1) Re-flowing Profile

Preheat condition: 150 ~200 ℃/60~180sec.

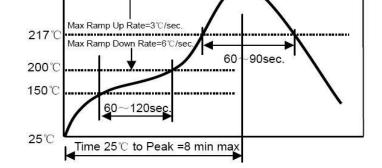
Allowed time above 217° : 80~120sec.

Max temp: 260°C

Max time at max temp: 10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Allowed Reflow time: 2x max



260℃

(2) Iron Soldering Profile

Iron soldering power: Max.

30W Pre-heating: 150°C/60sec.

Soldering time: 3sec. Max.

Solder paste: Sn/3.0Ag/0.5Cu

Max.1 times for iron soldering

